

Technical Data Sheet**High Performance SMD LED with Reflector****93-21SUGC/S400-A4/TR8****Features**

- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Eia std. package.
- IC compatible.
- Pb-free.
- The product itself will remain within RoHS compliant version.

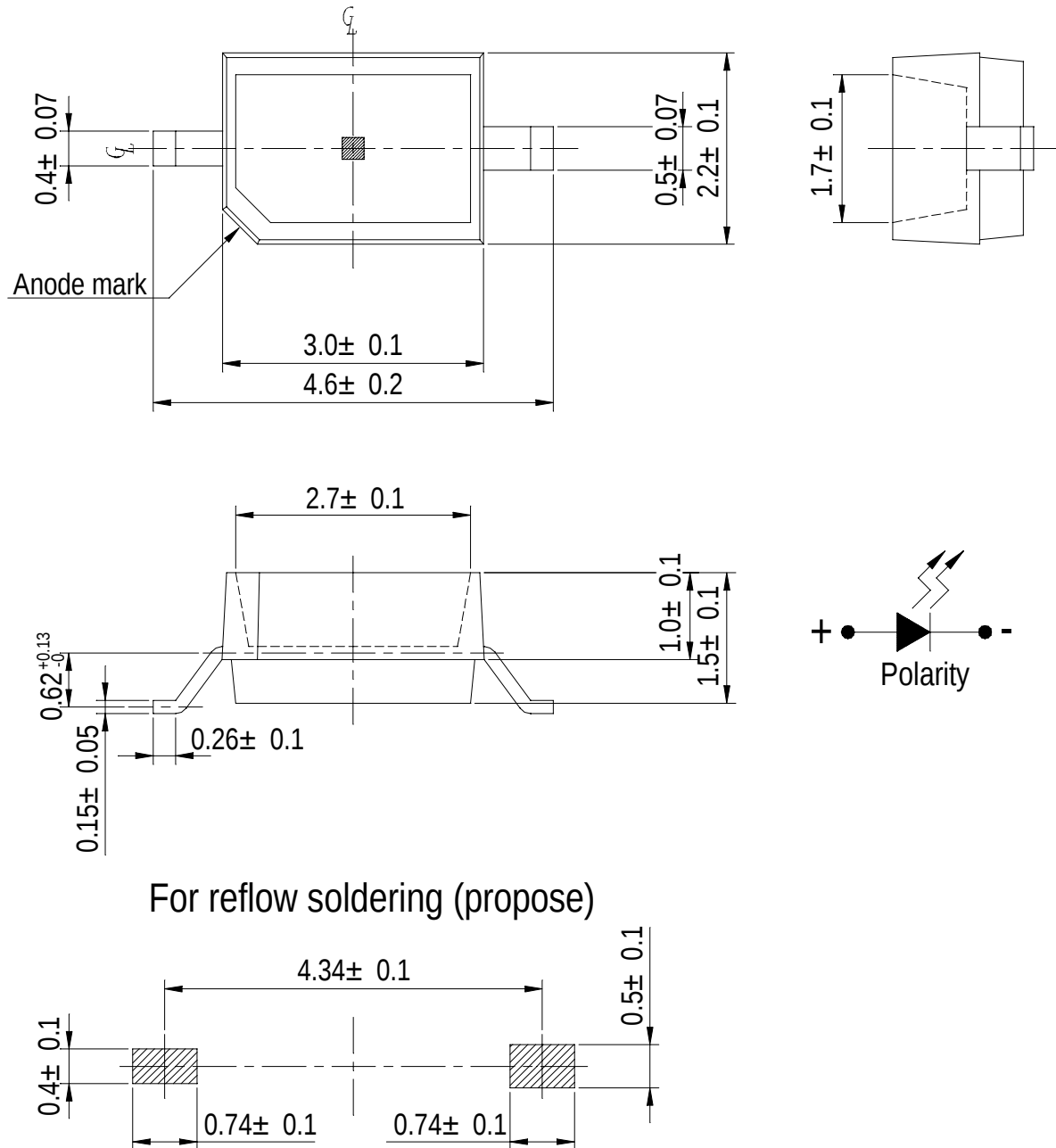
**Applications**

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Indicator and backlight for audio and video equipment
- Indicator and backlight for battery driven equipment.
- Flat backlight for LCD, switch and symbol.
- Light pipe application.
- General use.

Device Selection Guide

Chip		Lens Color
Material	Emitted Color	
InGaN	Brilliant Green	Water Clear

Package Dimensions



Notes: All dimensions are in millimeters.

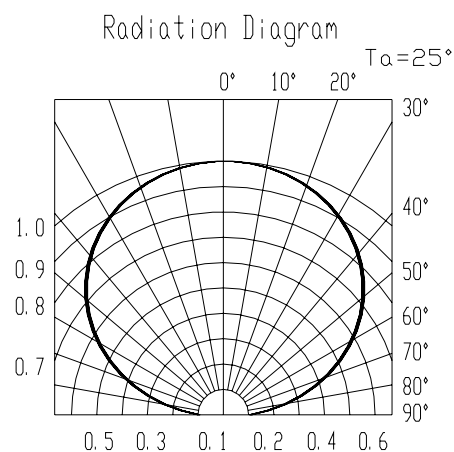
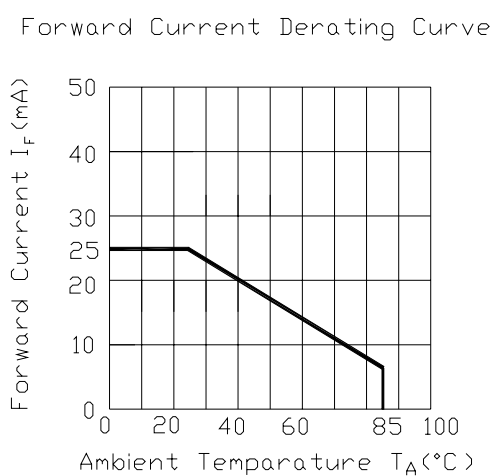
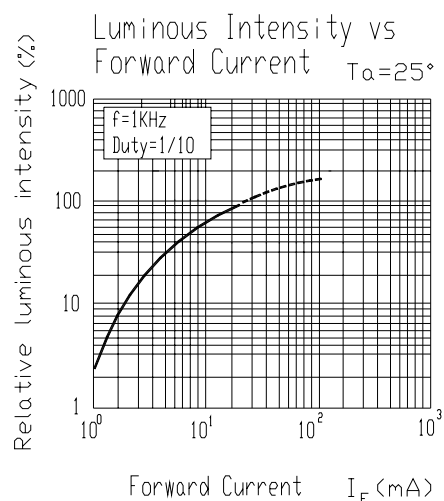
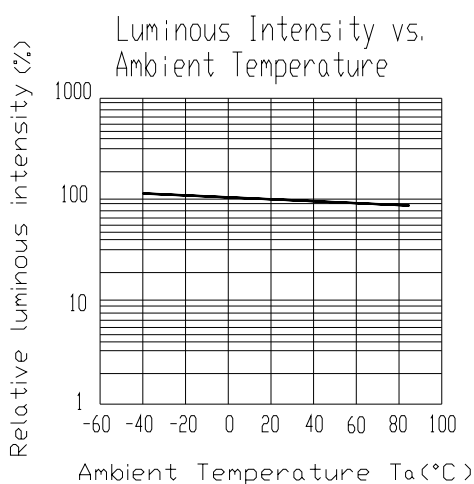
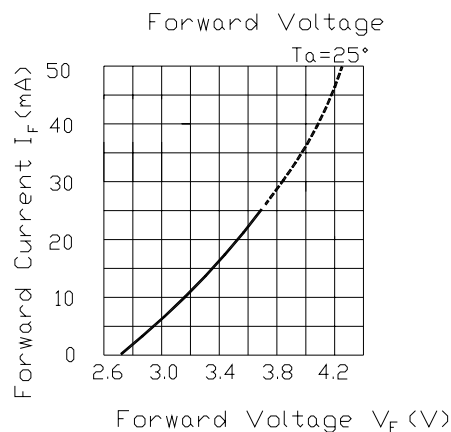
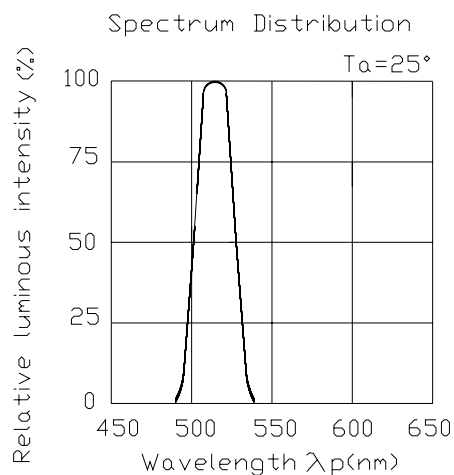
Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Electrostatic Discharge(HBM)	ESD	2000	V
Power Dissipation	P _d	110	mW
Peak Forward Current (Duty 1/10 @ 1KHz)	I _{FP}	100	mA
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous intensity	I _v	160	250	-----	mcd	I _F =20mA
Viewing Angle	2 θ 1/2	-----	130	-----	deg	I _F =20mA
Peak Wavelength	λ _p	-----	518	-----	nm	I _F =20mA
Dominant Wavelength	λ _d	-----	525	-----	nm	I _F =20mA
Spectrum Radiation Bandwidth	△ λ	-----	20	-----	nm	I _F =20mA
Forward Voltage	V _F	-----	3.5	4.3	V	I _F =20mA
Reverse Current	I _R	-----	-----	50	μ A	V _R =5V

Typical Electro-Optical Characteristics Curves



93-21SUGC/S400-A4/TR8

Label explanation

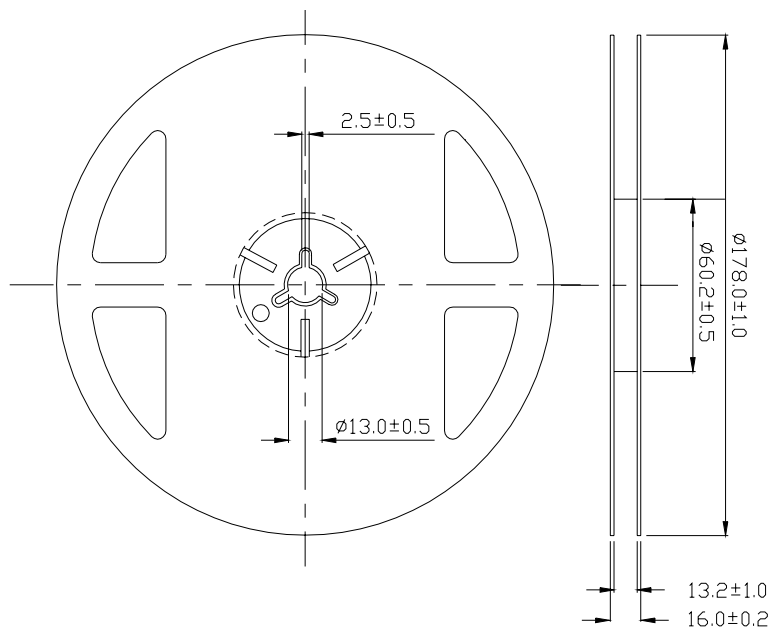
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

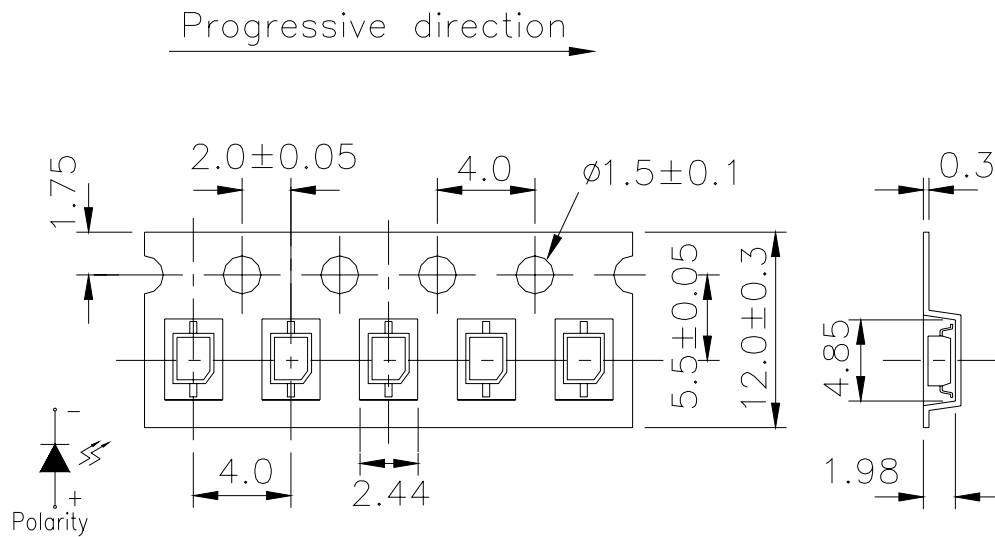
EVERLIGHT		
CPN: XXXXXX	P/N: XXXXXX	
XXXXXXXXXXXXXXXXXXXX		
QTY: XXXX		CAT:
LOT NO: XXXXXXXXXXXX		HUE:
		REF:
		
MADE IN TAIWAN		

Reel Dimensions



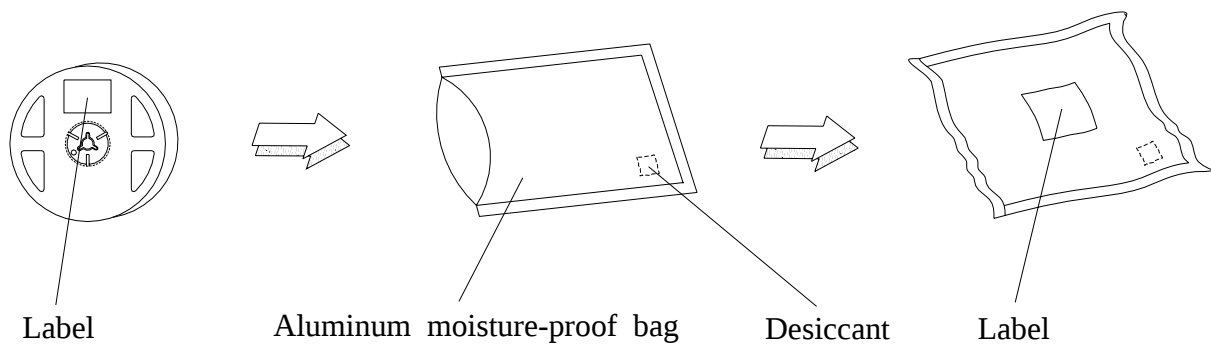
Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel.



TOLERANCES UNLESS DIMENSION±0.1
UNIT:mm

Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 min	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use**1. Over-current-proof**

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

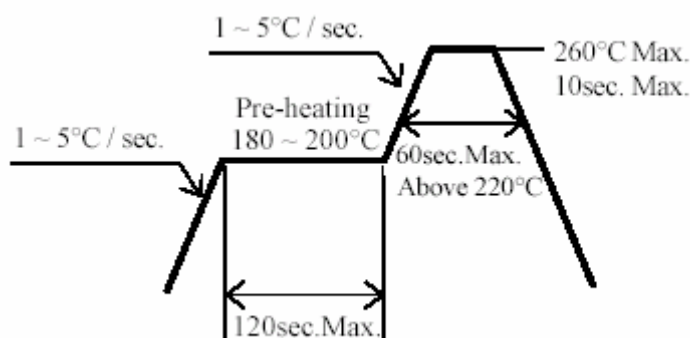
2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition**3.1 Pb-free solder temperature profile**

3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

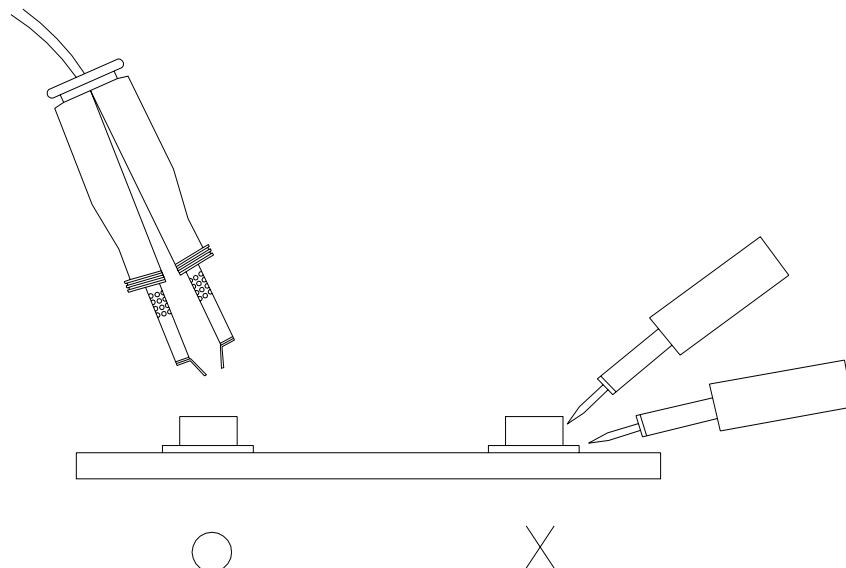
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

93-21SUGC/S400-A4/TR8**5.Repairing**

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

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